

OptiMOS® -T2 Power-Transistor

Product Summary

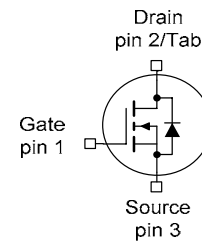
V_{DS}	60	V
$R_{DS(on),max}$	30	mΩ
I_D	25	A

Features

- N-channel - Enhancement mode
- AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested

PG-TO252-3-11


Type	Package	Marking
IPD25N06S4L-30	PG-TO252-3-11	4N06L30


Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25^\circ\text{C}, V_{GS}=10\text{V}$	25	A
		$T_C=100^\circ\text{C}, V_{GS}=10\text{V}^{1)}$	17	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C=25^\circ\text{C}$	92	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D=12.5\text{A}$	12	mJ
Avalanche current, single pulse	I_{AS}	-	25	A
Gate source voltage	V_{GS}	-	± 16	V
Power dissipation	P_{tot}	$T_C=25^\circ\text{C}$	29	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	-

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics²⁾						
Thermal resistance, junction - case	R_{thJC}	-	-	-	5.1	K/W
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm ² cooling area ³⁾	-	-	40	

Electrical characteristics, at $T_j=25^\circ\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=1mA$	60	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=8\mu A$	1.2	1.7	2.2	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V, T_j=25^\circ\text{C}$	-	0.01	1	μA
		$V_{DS}=60V, V_{GS}=0V, T_j=125^\circ\text{C}^2)$	-	5	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=16V, V_{DS}=0V$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=12.5A$	-	36	56	m Ω
		$V_{GS}=10V, I_D=25A$	-	23	30	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics²⁾

Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=25V,$ $f=1MHz$	-	935	1220	pF
Output capacitance	C_{oss}		-	265	345	
Reverse transfer capacitance	C_{rss}		-	13	32	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=30V, V_{GS}=10V,$ $I_D=25A, R_G=3.5\Omega$	-	6	-	ns
Rise time	t_r		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	15	-	
Fall time	t_f		-	2	-	

Gate Charge Characteristics²⁾

Gate to source charge	Q_{gs}	$V_{DD}=48V, I_D=25A,$ $V_{GS}=0$ to 10V	-	3.9	5.1	nC
Gate to drain charge	Q_{gd}		-	1.6	3.2	
Gate charge total	Q_g		-	12.5	16.3	
Gate plateau voltage	$V_{plateau}$		-	4.2	-	V

Reverse Diode

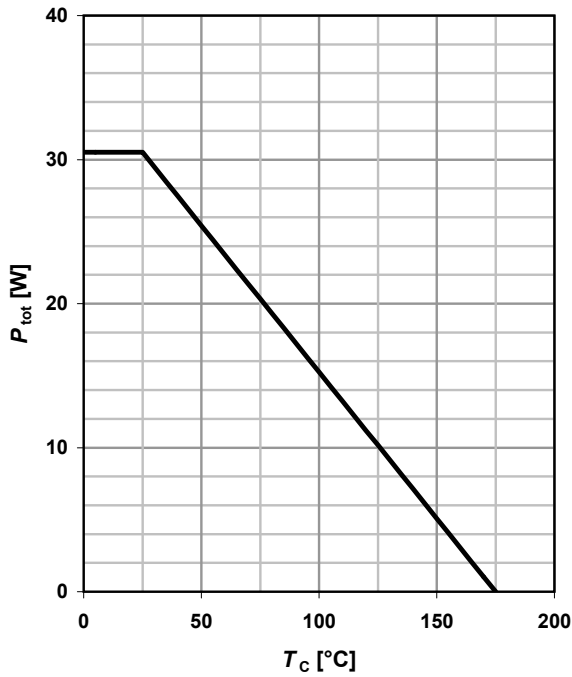
Diode continuous forward current ²⁾	I_S	$T_C=25^\circ C$	-	-	25	A
Diode pulse current ²⁾	$I_{S,pulse}$		-	-	100	
Diode forward voltage	V_{SD}	$V_{GS}=0V, I_F=25A,$ $T_j=25^\circ C$	0.6	0.95	1.3	V
Reverse recovery time ²⁾	t_{rr}	$V_R=30V, I_F=I_S,$ $di_F/dt=100A/\mu s$	-	8	-	ns
Reverse recovery charge ²⁾	Q_{rr}		-	8	-	

¹⁾ Specified by design. Not subject to production test.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

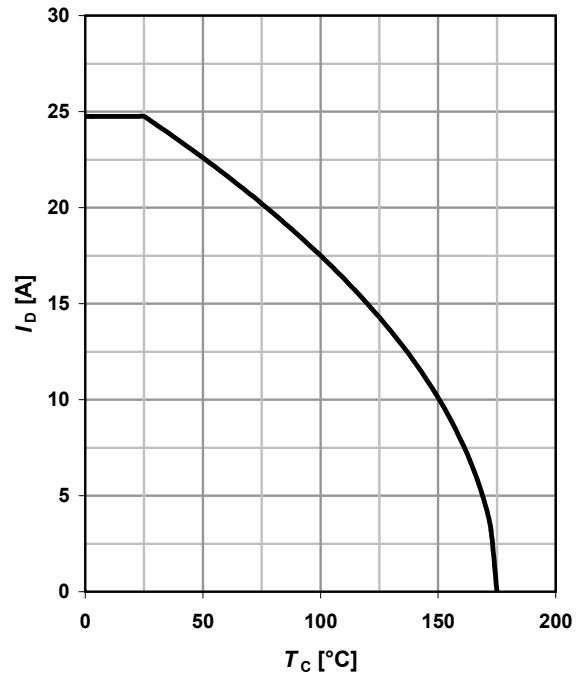
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 6\text{ V}$



2 Drain current

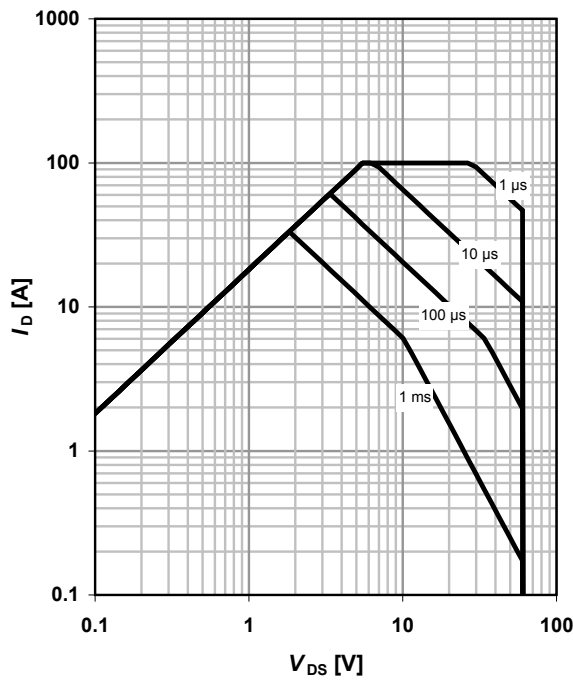
$I_D = f(T_C); V_{GS} \geq 6\text{ V}$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

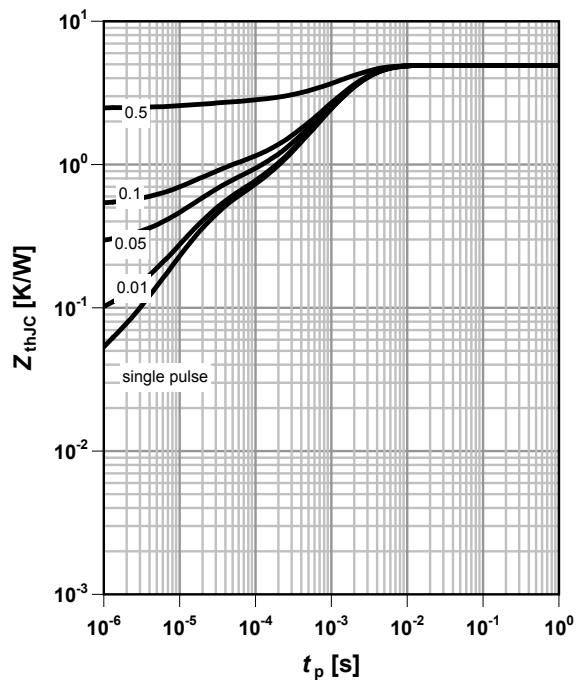
parameter: t_p



4 Max. transient thermal impedance

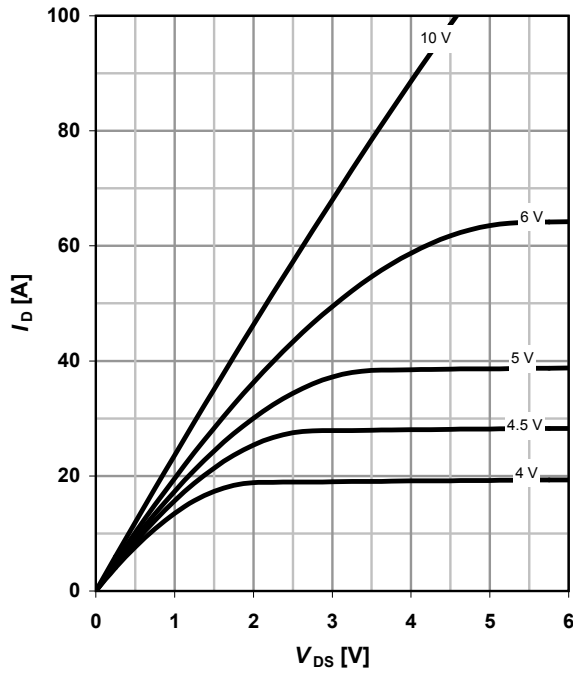
$Z_{thJC} = f(t_p)$

parameter: $D = t_p/T$

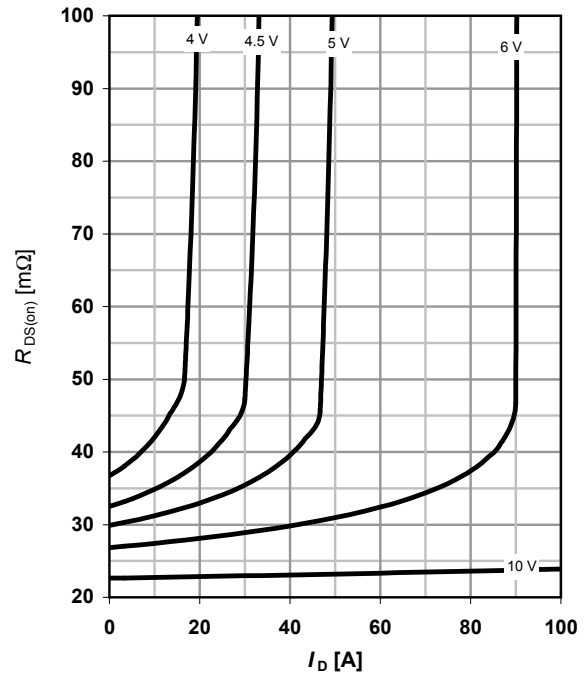


5 Typ. output characteristics

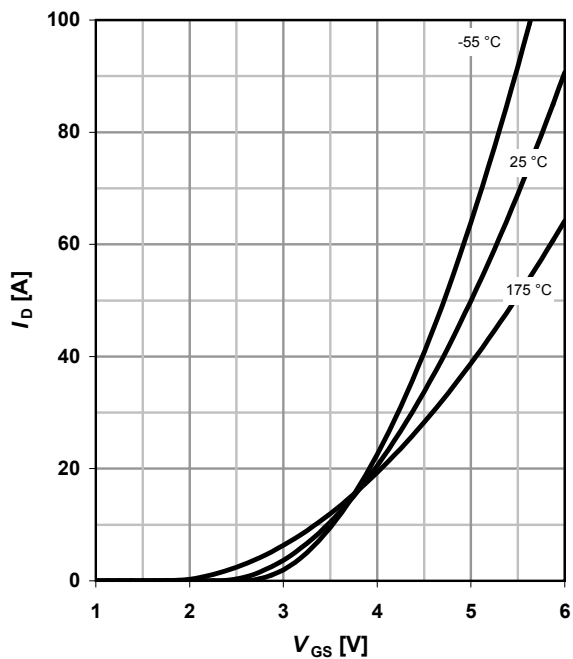
$$I_D = f(V_{DS}); T_j = 25\text{ °C}$$

 parameter: V_{GS}

6 Typ. drain-source on-state resistance

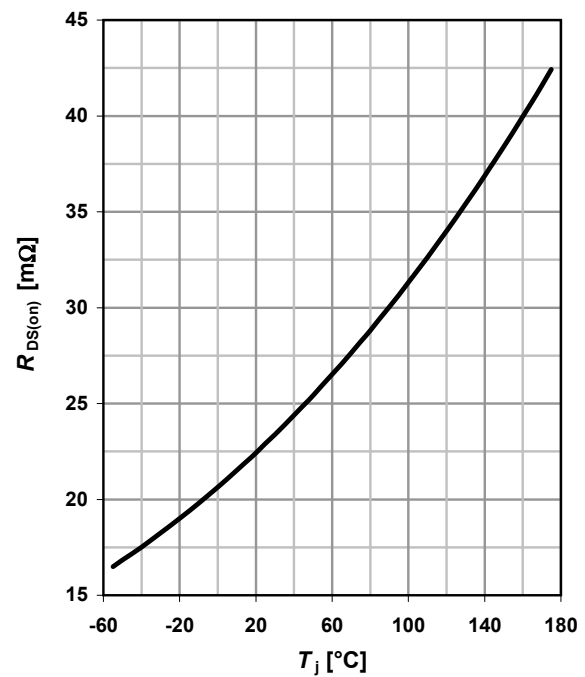
$$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$$

 parameter: V_{GS}

7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$$

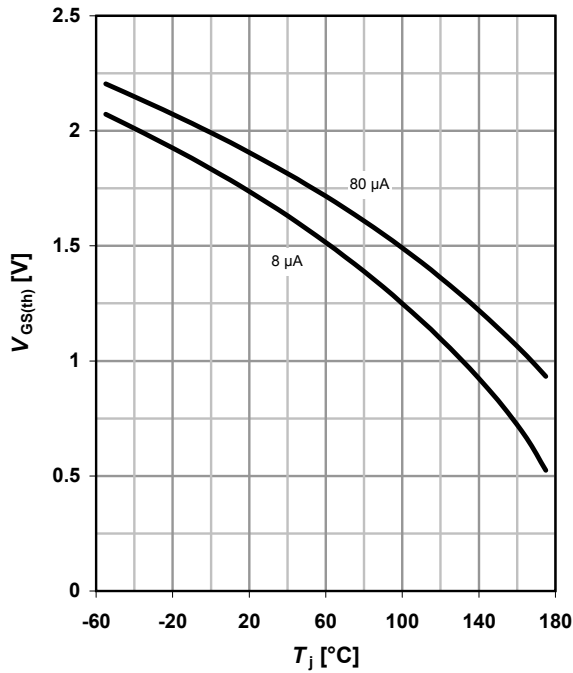
 parameter: T_j

8 Typ. drain-source on-state resistance

$$R_{DS(on)} = f(T_j); I_D = 25\text{ A}; V_{GS} = 10\text{ V}$$

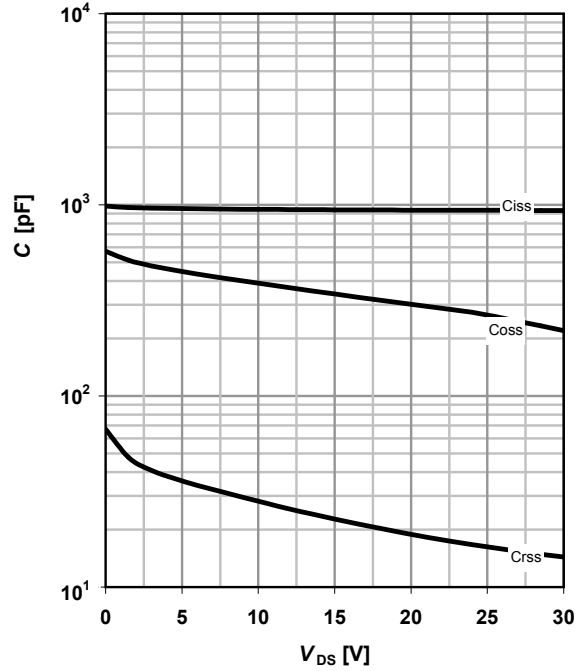


9 Typ. gate threshold voltage

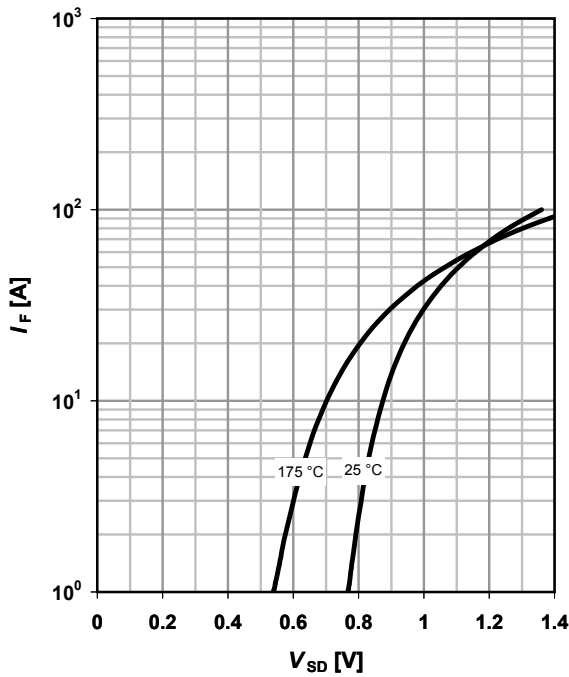
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

 parameter: I_D

10 Typ. capacitances

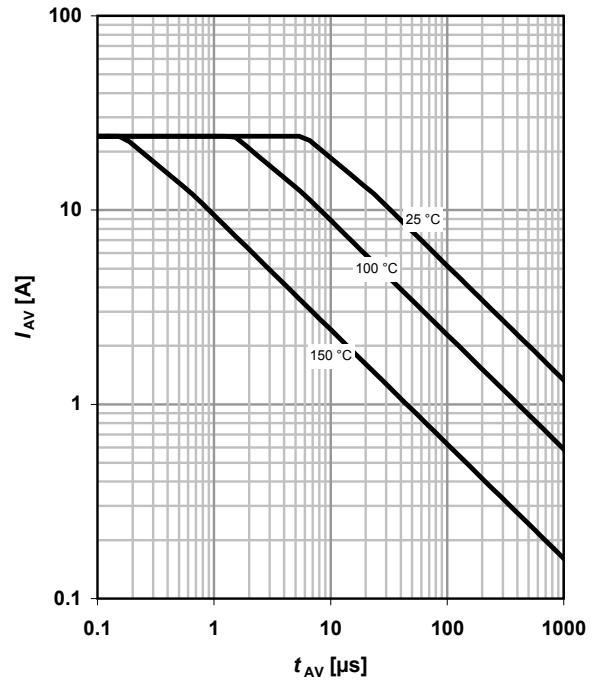
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$


11 Typical forward diode characteristics

$$I_F = f(V_{SD})$$

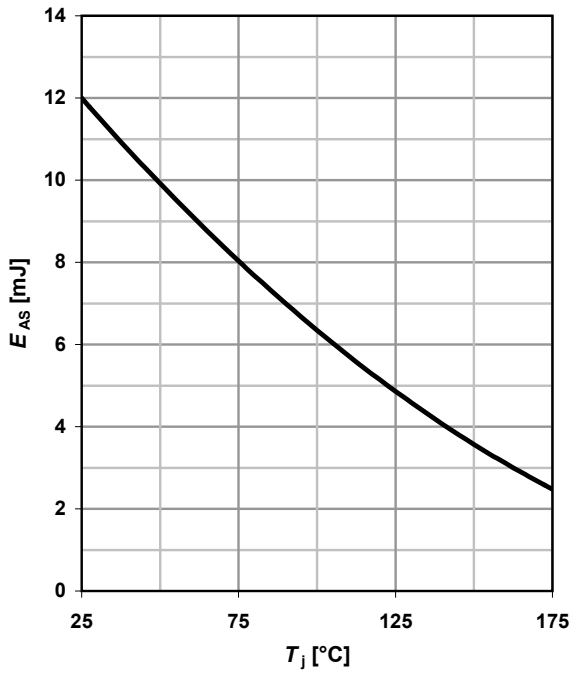
 parameter: T_j

12 Avalanche characteristics

$$I_{AS} = f(t_{AV})$$

 parameter: $T_{j(start)}$


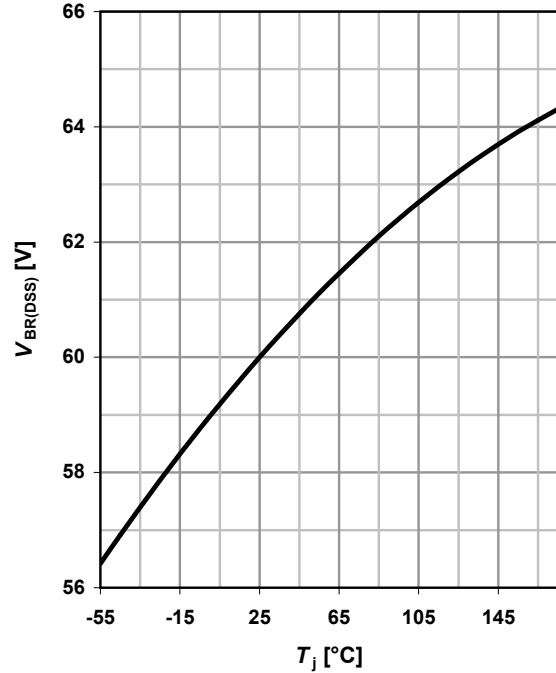
13 Avalanche energy

$E_{AS} = f(T_j); I_D = 12.5 \text{ A}$



14 Drain-source breakdown voltage

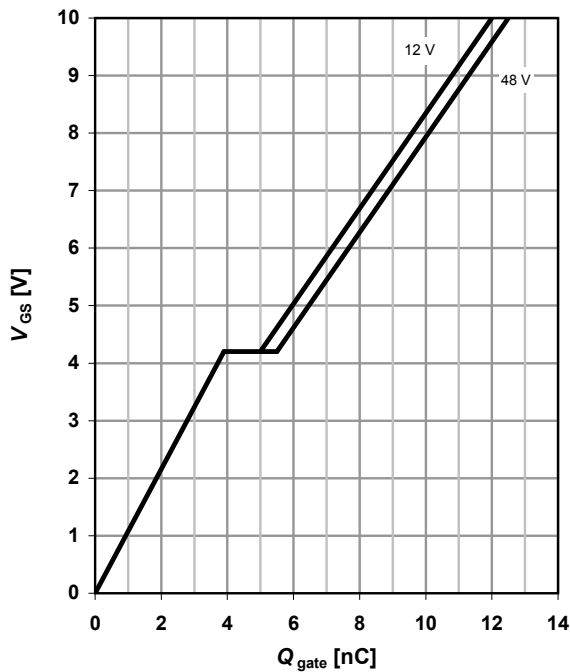
$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$



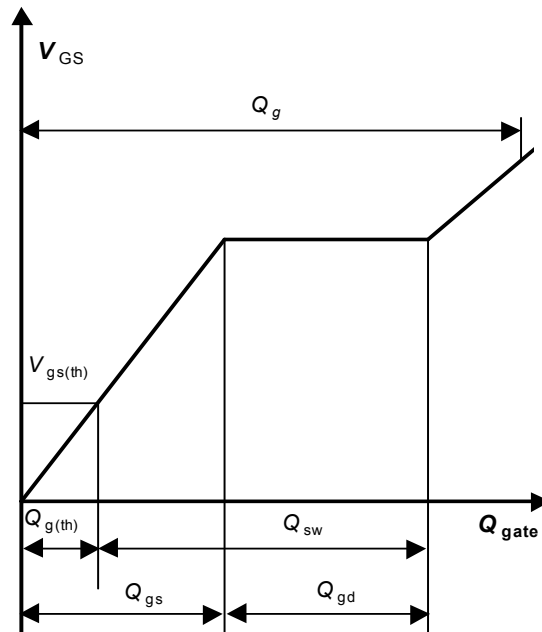
15 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = 25 \text{ A pulsed}$

parameter: V_{DD}



16 Gate charge waveforms



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Infineon Technologies AG
81726 Munich, Germany

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Revision History

Version	Date	Changes
Revision 1.0	23.03.2009	Final data sheet